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01 TRACKS & TOPICS *topics include, but are not limited to*

- 1 Artificial Intelligence, Machine Learning, and Cybersecurity
- 2 Data Science & Analytics, Digital Twins, and Business Analytics
- 3 Communication Systems, Networking, and Cloud Computing
- 4 Internet of Things, Smart Sensing, Smart Grids & Smart Energy, and Edge Computing
- 5 Electronics, Circuits, and Systems
- 6 Smart Civil & Architectural Engineering, Intelligent Transportation Systems, and GIS
- 7 Emerging Trends in Mechanical, Industrial, and Robotics Engineering
- 8 Digital Transformation in Education, Business, Management & Finance

02 IMPORTANT DATES



Author Guidelines

- Use the standard **IEEE double-column format (A4)** – Word or LaTeX template.
- Length: **4–6 pages**, including references; written in English.
- Original, unpublished work not under review elsewhere.
- At least one author must **register and present** the accepted paper.

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